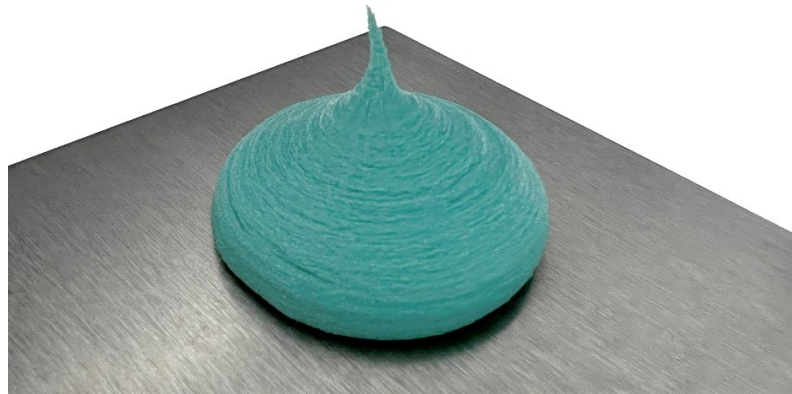




Thermal Gel 21-340-SP01

FEATURES & BENEFITS

- Thermal Conductivity: 3.5 W/m-K
- Soft and Compliant Transferring Little To No Pressure Between Interfaces
- Easily Dispensable
- Pre-Cured
- Electrically Isolating
- Low Thermal Resistance



APPLICATIONS

- Cooling components to chassis, frame, or other mating components
- Memory modules
- Mass storage devices
- Automotive electronics
- Telecommunication hardware
- Power electronics
- LCD and PDP flat panel
- Audio and video component
- IT infrastructure
- GPS navigation and other portable devices

JONES Thermal Gel 21-340-SP01 is a soft, single part, silicone putty thermal gap filler in which no cure is required. This gap filler is designed to be used in where large gap tolerances presently and low mechanical stress on delicate components . It is ideal for filling variable gaps between multiple components and a common heat sink.

JONES Thermal Gel 21-340-SP01 has superior thermal performance and super compliancy. It provides outstanding reliability. Specialized rheology allows for easy flow under pressure.

TYPICAL PROPERTIES

| | Properties | Thermal Gel 21-340-SP01 | Test Method |
|------------|---|-------------------------|--|
| Thermal | Thermal Conductivity (W/m-K) | 3.5 | ASTM D5470 |
| | Thermal Resistance ($^{\circ}\text{C}\cdot\text{cm}^2/\text{W}$) @1mm | - | ASTM D5470 |
| | Operating Temperature Range ($^{\circ}\text{C}$) | -55~150 | JONES Test Method |
| Physical | Color | Green | Visual |
| | Composition | Ceramic & Silicone | - |
| | Density (g/cc) | 3.2 | ASTM D792 |
| | Flow Rate (g/min) | 48 | 90 Psi,EFD 180cc @ \varnothing 3.17mm nozzle |
| | Typical Minimum Bondline Thickness (mm) | 0.10 | JONES Test Method |
| Electrical | Breakdown Voltage (KV AC /mm) | > 5 | ASTM D149 |
| | Volume Resistivity (Ohm-cm) | 10^{13} | ASTM D257 |
| | Dielectric Constant @1MHz | 5.0 | ASTM D150 |
| Regulatory | Flammability Rating | V0 | UL 94 |

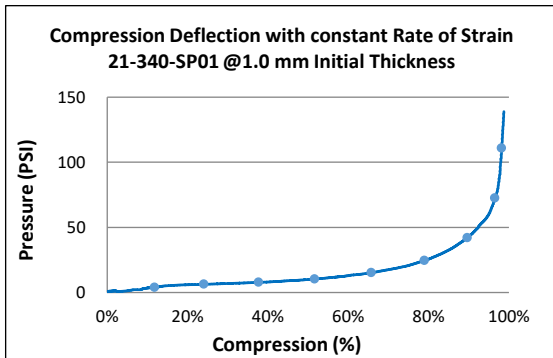


TEST RESULTS

21-340-SP01 Thermal Gel 1.0 mm Initial Thickness; 1 inch² Specimen Area;

Compression Deflection

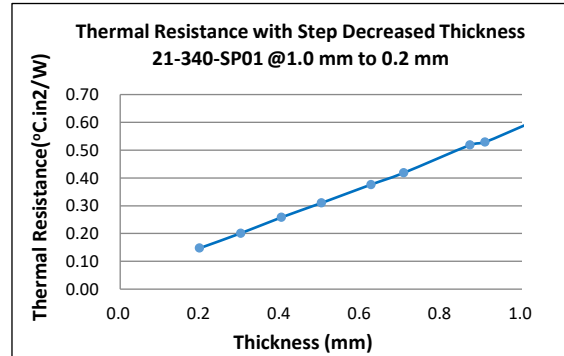
Rate of strain = 1.0 mm/min



*Test Before Curing

Thermal Resistance

Decreased Thickness step = 0.2 mm



PART NUMBER SYSTEM

21 - 3 XX - AB - YYY

① ② ③ ④ ⑤

- ① 21-Thermal management material
- ② 3- Thermal Gel
- ③ XX- Thermal Performance
- ④ AB- Optional style
- ⑤ YYY- Package Size



ORDERING INFORMATION

Part Number Examples

21-340-SP01-010-800G=Thermal Gel 21-340-SP01 in a 300 cc Cartridge (800 g)

21-340-SP01-080-25KG=Thermal Gel 21-340-SP01 in a 5 Gallon Pail (25 Kg)

Customizable packaging

Storage Requirement

0°C to 35°C, 50%RH, sealing preservation

18 months from date of manufacture.

* Unopened Original Package

HANDLING PRECAUTIONS

FOR SAFE HANDLING INFORMATION OF THIS PRODUCT, PLEASE CONTACT WITH YOUR JONES REPRESENTATIVE FOR THE SAFETY DATA SHEET (SDS).

LIMITED WARRANTY INFORMATION

The information provided in this Technical Data Sheet including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the data of this TDS. Jones Corp is not, therefore, liable for the suitability of any Jones Corp products for any specific or general uses. Jones Corp shall not be liable for incidental or consequential damages of any kind.

FOR MORE INFORMATION

About our high performance materials, solutions and capabilities, please visit our website:

<http://www.jones-corp.com>

Disclaimer

- The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the issuing date of this TDS. When using our products, no matter what type of equipment they might be used for, be sure to make a written agreement on the specifications with us in advance. The design and specifications in this TDS are subject to change without prior notice.
- Do not use the products beyond the specifications described in this TDS. This TDS explains the typical performance of the products as individual component. Before use, check and evaluate their operations when installed in your products.
- The product provided in this TDS compliance with HSF.

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